

## ABSTRACT OF THE DISCLOSURE

A semiconductor integrated circuit device which requires high packaging density adopts a method for forming  
5 bumps in a terminal section of a semiconductor chip and bonding  
the semiconductor chip directly on a substrate. In this case,  
in order to prevent damage to the semiconductor integrated  
chip, which would otherwise be caused by bonding pressure  
employed at the time of bonding operation, non-connected dummy  
10 bumps are provided at corner sections of the semiconductor  
chip. Even when the dummy bumps are provided, there arises  
a necessity for preventing an increase in the size of the  
semiconductor chips, which would otherwise arise when the dummy  
bumps are provided on the chip.